

Application Serial No: 10/523,547
Responsive to the Final Office Action mailed on: July 27, 2007

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IN THE CLAIMS

Amendments To The Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Previously Presented) A method for manufacturing a capacitor element for a solid electrolytic capacitor comprising the steps of:
 - forming a porous anode chip body by solidly molding a powder of a valve-acting metal, and then sintering the same;
 - adhesively attaching one end surface of said anode chip body to a surface of a metal plate with an electrically conductive adhesive, so that the anode chip body can be peeled off from the metal plate;
 - successively forming a dielectric film, a solid electrolyte layer, and a cathode-side electrode film, in this order, on the anode chip body adhesively attached to said metal plate; and
 - separating said anode chip body from said metal plate.
2. (Previously Presented) The method for manufacturing a capacitor element for a solid electrolytic capacitor according to claim 1, further comprising the steps of:
 - forming a coating film of a water-repellent synthetic resin on said surface of said metal plate so as to seal said one end surface of said anode chip body with said coating film, between the steps of adhesively attaching said one end surface of said anode chip body to said surface of the metal plate; and
 - forming the dielectric film, the solid electrolyte layer, and the cathode-side electrode film on the anode chip body.
3. (Previously Presented) A method for manufacturing a solid electrolytic capacitor comprising manufacturing a capacitor element via the steps of:

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forming a porous anode chip body by solidly molding a powder of a valve-acting metal, and then sintering the same;

adhesively attaching one end surface of said anode chip body to a surface of a metal plate with an electrically conductive adhesive, so that the anode chip body can be peeled off from the metal plate;

successively forming a dielectric film, a solid electrolyte layer, and a cathode-side electrode film, in this order, on the anode chip body adhesively attached to said metal plate;

separating said anode chip body from said metal plate;

providing an anode-side terminal on said one end surface of the anode chip body and providing a cathode-side terminal on the cathode-side electrode film of the anode chip body; and

packaging the entire said capacitor element with a synthetic resin.

Claims 4-5. (Cancelled)